

ELECTRICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum forward voltage drop See fig. 1	V _{FM} ⁽¹⁾	3 A	T _J = 25 °C	0.81	V
		6 A		0.96	
		3 A	T _J = 125 °C	0.63	
		6 A		0.74	
Maximum reverse leakage current See fig. 2	I _{RM} ⁽¹⁾	T _J = 25 °C	V _R = Rated V _R	1	mA
		T _J = 125 °C		4.9	
Threshold voltage	V _{F(TO)}	T _J = T _J maximum		0.48	V
Forward slope resistance	r _t			30.89	mΩ
Typical junction capacitance	C _T	V _R = 5 V _{DC} (test signal range 100 kHz to 1 MHz), 25 °C		92	pF
Typical series inductance	L _S	Measured lead to lead 5 mm from package body		5.0	nH
Maximum voltage rate of change	dV/dt	Rated V _R		10 000	V/μs

Note

⁽¹⁾ Pulse width < 300 μs, duty cycle < 2 %

THERMAL - MECHANICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	$T_J^{(1)}, T_{Stg}$		- 40 to 150	°C
Maximum thermal resistance, junction to case	R_{thJC}	DC operation See fig. 4	4.7	°C/W
Approximate weight			0.3	g
			0.01	oz.
Marking device		Case style D-PAK (similar to TO-252AA)	30WQ10FN	

Note

⁽¹⁾ $\frac{dP_{tot}}{dT_J} < \frac{1}{R_{thJA}}$ thermal runaway condition for a diode on its own heatsink

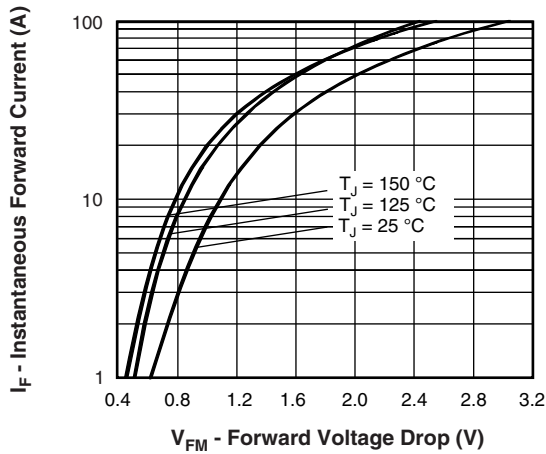


Fig. 1 - Maximum Forward Voltage Drop Characteristics

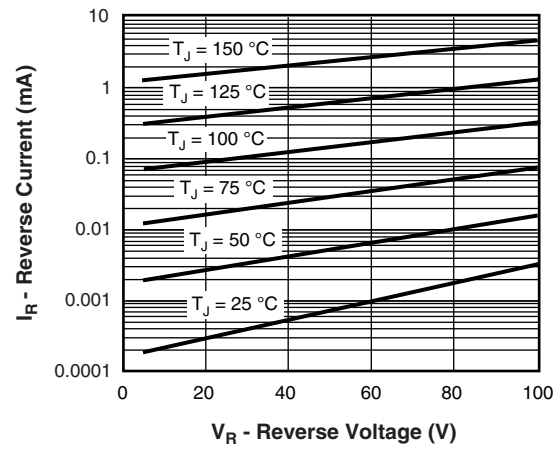


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

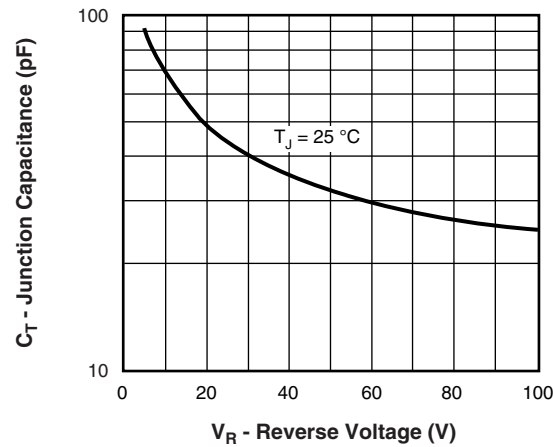
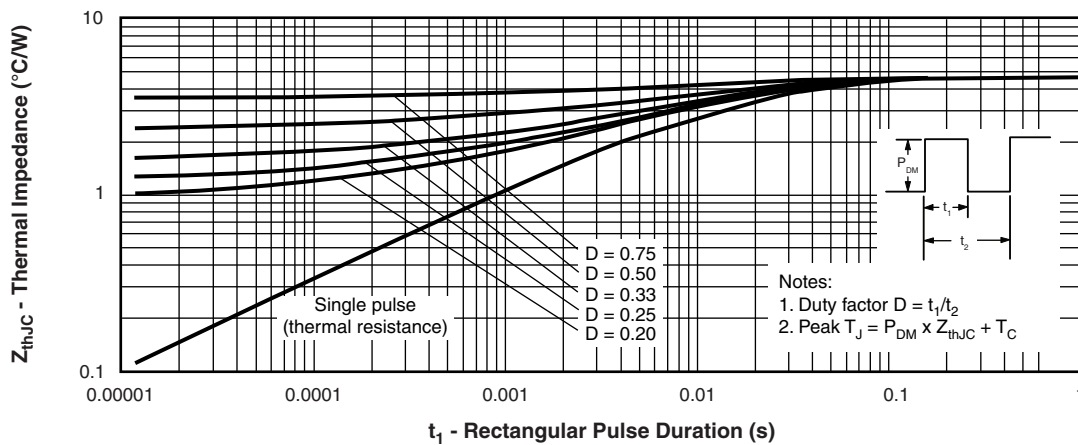


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

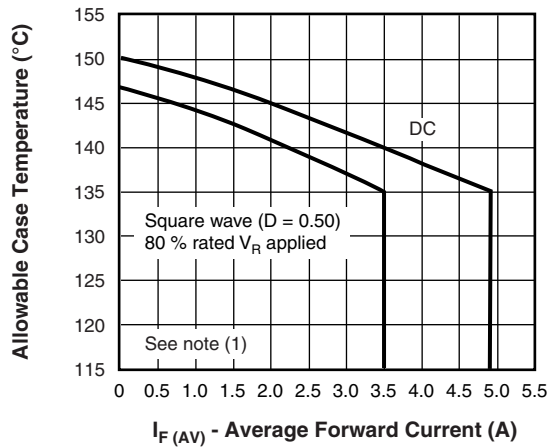


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

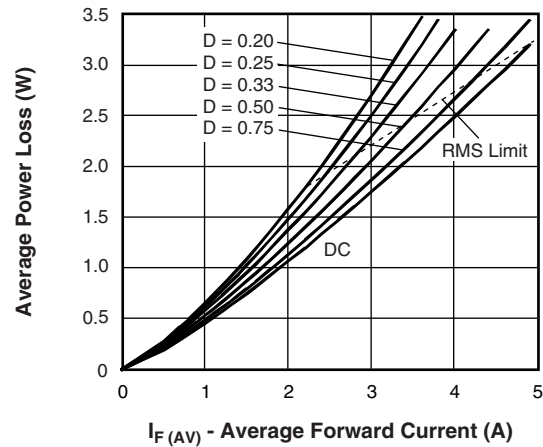


Fig. 6 - Forward Power Loss Characteristics

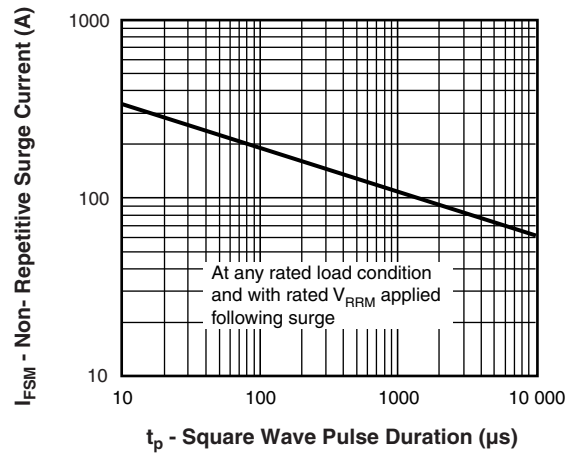


Fig. 7 - Maximum Non-Repetitive Surge Current

Note

- (1) Formula used: $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$;
 P_d = Forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 6);
 P_{dREV} = Inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at $V_{R1} = 80\%$ rated V_R

**ORDERING INFORMATION TABLE**

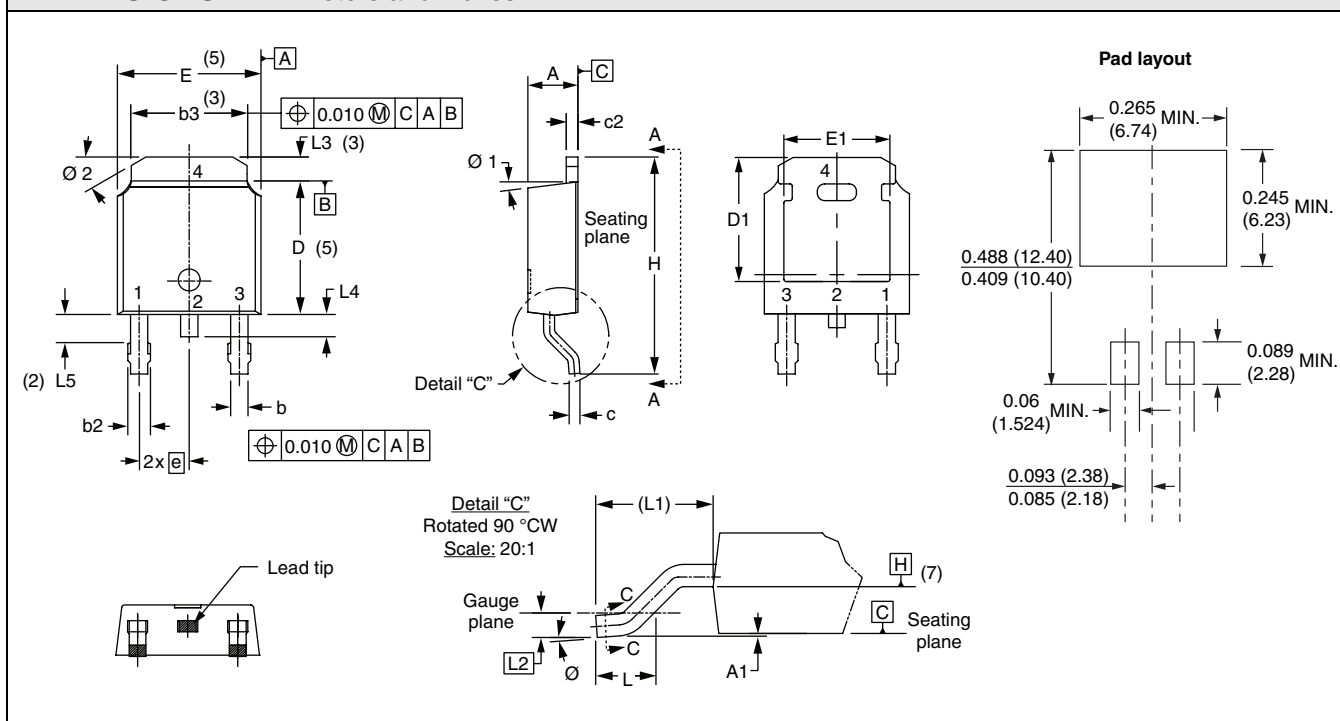
Device code	VS-	30	W	Q	10	FN	TRL	PbF
	①	②	③	④	⑤	⑥	⑦	⑧

- | | |
|----------|---|
| 1 | - Vishay Semiconductors product |
| 2 | - Current rating (3.5 A) |
| 3 | - Package identifier:
W = D-PAK |
| 4 | - Schottky "Q" series |
| 5 | - Voltage rating (10 = 100 V) |
| 6 | - FN = TO-252AA (D-PAK) |
| 7 | - <ul style="list-style-type: none">• None = Tube (50 pieces)• TR = Tape and reel• TRL = Tape and reel (left oriented)• TRR = Tape and reel (right oriented) |
| 8 | - PbF = Lead (Pb)-free |

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95016
Part marking information	www.vishay.com/doc?95059
Packaging information	www.vishay.com/doc?95033

D-PAK (TO-252AA)

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	2.18	2.39	0.086	0.094	
A1	-	0.13	-	0.005	
b	0.64	0.89	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	3
c	0.46	0.61	0.018	0.024	
c2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	5
D1	5.21	-	0.205	-	3
E	6.35	6.73	0.250	0.265	5
E1	4.32	-	0.170	-	3

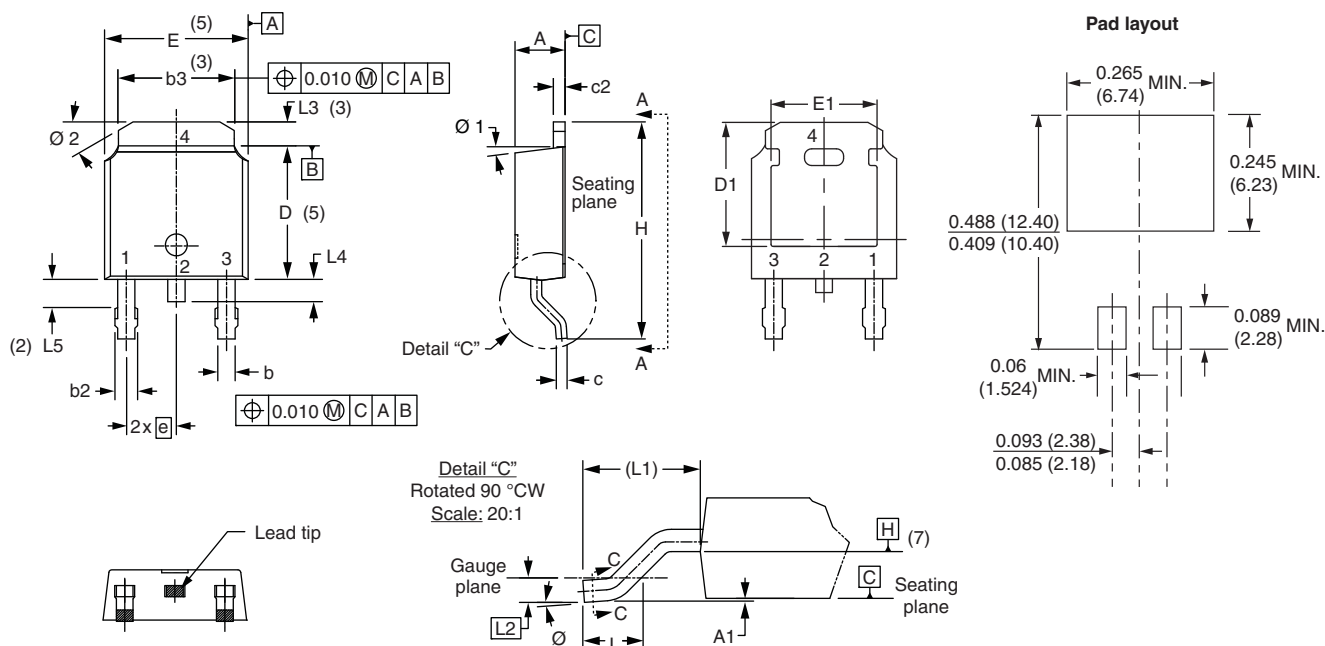
SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
e	2.29 BSC		0.090 BSC		
H	9.40	10.41	0.370	0.410	
L	1.40	1.78	0.055	0.070	
L1	2.74 BSC		0.108 REF.		
L2	0.51 BSC		0.020 BSC		
L3	0.89	1.27	0.035	0.050	3
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	2
Ø	0°	10°	0°	10°	
Ø1	0°	15°	0°	15°	
Ø2	25°	35°	25°	35°	

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension uncontrolled in L5
- (3) Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad
- (4) Section C - C dimension apply to the flat section of the lead between 0.13 and 0.25 mm (0.005 and 0.10") from the lead tip
- (5) Dimension D, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (6) Dimension b1 and c1 applied to base metal only
- (7) Datum A and B to be determined at datum plane H
- (8) Outline conforms to JEDEC outline TQ-252AA

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- Outline conforms to JEDEC outline TO-252AA



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